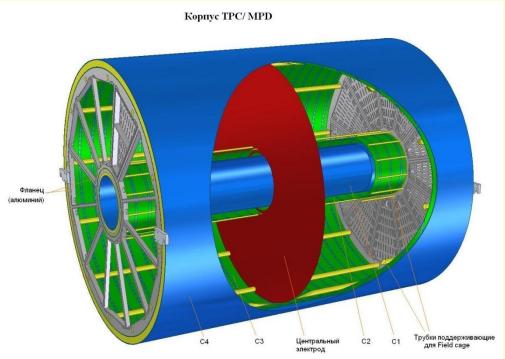
## **TPC status (12.04.2018)**

- TPC assembly hall
- tooling for TPC assembly
- ROC chambers
- front end electronics: SAMPA and analog options
- sub-systems: gas, cooling and laser calibration
- integration TPC to MPD
- time schedule

## **Presented by Sergey Movchan**

TPC TDR rev.06 - <a href="http://mpd.jinr.ru/wp-content/uploads/2017/05/TDR">http://mpd.jinr.ru/wp-content/uploads/2017/05/TDR</a> TPC v6 2017.pdf

# **MPD TPC parameters**



Item	Dimension
Length of the TPC	340cm
Outer radius of vessel	140cm
Inner radius of vessel	27 cm
Outer radius of the drift	133cm
volume	
Inner radius of the drift	34cm
volume	
Length of the drift	170cm (of each half)
volume	
HV electrode	Membrane at the center of the TPC
<b>Electric field strength</b>	~140V/cm;
Magnetic field strength	0.5 Tesla
Drift gas	90% Ar+10% Methane, Atmospheric pres.
	+ 2 mbar
Gas amplification factor	~ 104
Drift velocity	5.45 cm/μs;
Drift time	< 30μs;
Temperature stability	< 0.5°C
Number of readout	24 (12 per each end-plate)
chambers	
Segmentation in φ	30°
Pad size	5x12mm <sup>2</sup> and 5x18mm <sup>2</sup>
Number of pads	95232
Pad raw numbers	53
Pad numbers after zero	< 10%
suppression	
Maximal event rate	< 7 kHz ( Lum. 10 <sup>27</sup> )
Electronics shaping time	~180 ns (FWHM)
Signal-to-noise ratio	30:1
Signal dynamical range	10 bits
Sampling rate	10 MHz
Sampling depth	310 time buckets

## TPC assembly hall (LHEP, bld.217) – common view





## **Clean room**

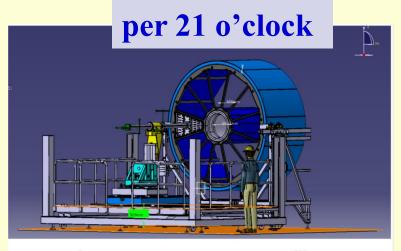


## Ready

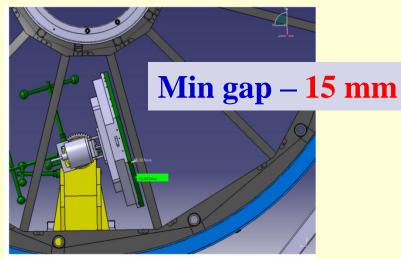
## Briansk: manipulator for ROC chamber installation

Top chamber

Высота от пола до подьемника составила примерно 1243 mm.



Высота от пола до подъемника составила примерно 503mm.





## **TPC flanges: leak test**

# Set up



## Pressure drop measurement



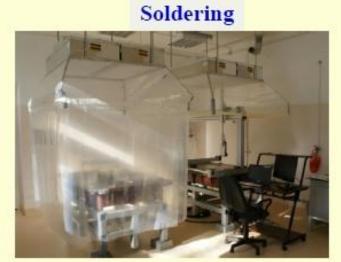
tested

## **ROC** chamber assembly facility



Wiring

Test set up



S.Movchan MPD TPC status

**Bld.40** 

## **ROC** chambers: test set up

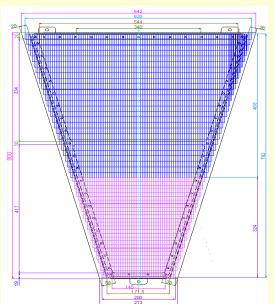


## **Test procedure:**

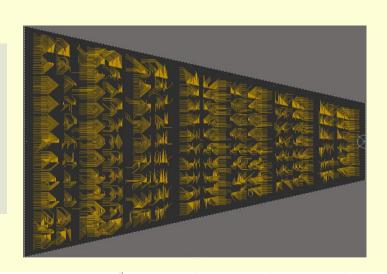
- counting plateau
- dark current
- energy resolution (Fe-55)
- uniformity of gas gain
  - ✓ linear scan
  - ✓ area scan

pre-serial ROC chamber: tested

## Pad plane

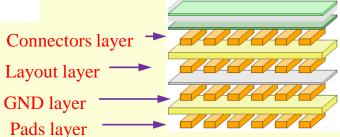


Pads dimensions and quantity are determined by experiment requirements on space and momentum resolutions.



#### Pad structure:

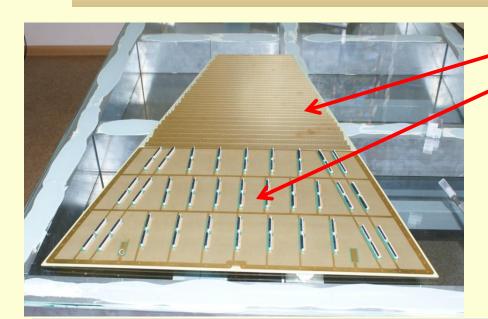
- pad raw number 53 rectangle shape
- small pads 5×12 mm<sup>2</sup>
- large pads 5×18 mm<sup>2</sup>



Layer Name	Туре	Material	Thickness (mm)	
Top Overlay	Overlay			
Top Solder	Solder Mask/Co	Surface Material	0.01016	
Top Layer	Signal	Copper	0.018	
Dielectric1	Dielectric	Core	1	
Signal Layer 1	Signal	Copper	0.035	
Dielectric2	Dielectric	Prepreg	1	
Signal Layer 2	Signal	Copper	0.035	
Dielectric3	Dielectric	Core	1	
Bottom Layer	Signal	Copper	0.018	

## quality is no so good ... 2 new ordered (China and Italy)

## From PCB technology: pad plane from 2 parts



# Pads capacitor measurement



Pad plane bending, thickness – more less ok Some pad capacitor – 300 pF instead 20 pF ??? Measurements and tests – in progress

New pad plane from Italy – April 30 2018

#### Read out electronics status

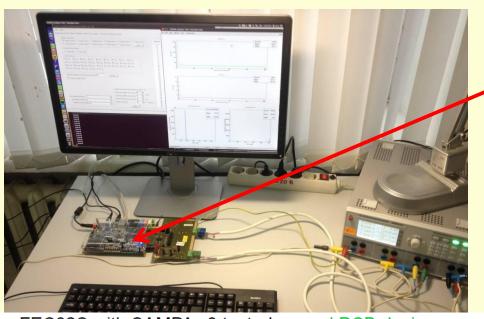
#### **FE** electronics:

- SAMPA - base line option (FEC32S, FEC64SAM v1, v2)

Low voltage distribution board (LVDB)

Data concentrator and server - looking on ALICE RCU

## MPD TPC FE based on SAMPA chip

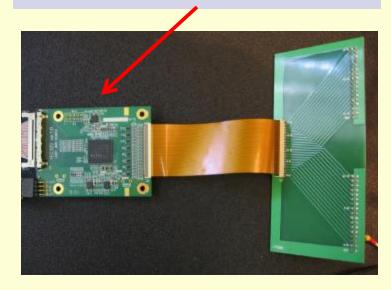


**Tests of SAMPA chip (rev.2) – done** 

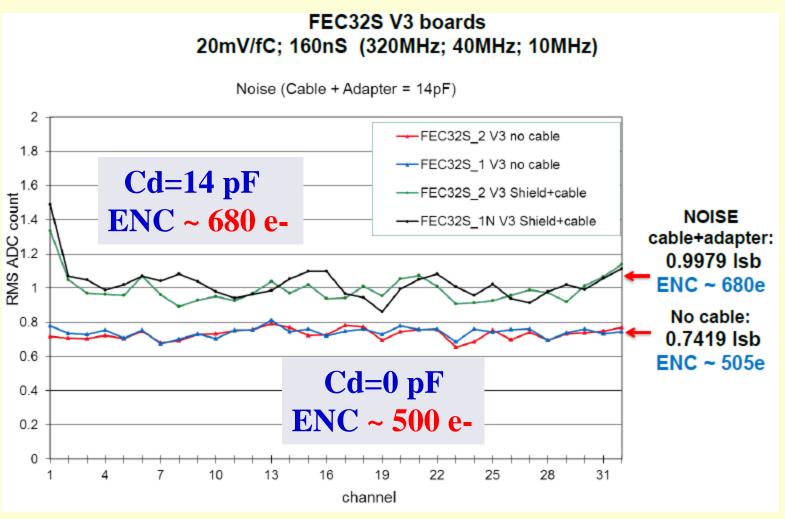
Tests of SAMPA chip (rev.3) – done, 27 pc good

- FEC32S with SAMPA v3 tested good PCB design
- Main tests works good
- Measured SAMPA V3 noise is good < 0.8 lsb</li>
- Measured pedestals for all chips were in the expected range
- The Gain is inside specification (19,4 19,8)
- The Peaking Time is inside specification (165 175nS)
- POR circuit works
- Vref average = 755; 602; 451mV for ADCTRIM=05
- Power diss. < 32 mW/channel (1054 mW full board)</li>

#### **MPD TPC FEC32S board:**

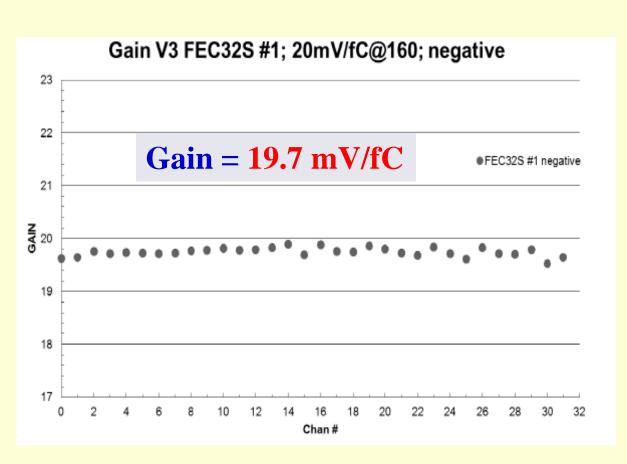


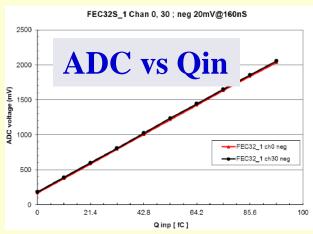
## **Noise** measurement (for Cd=0 pF): results

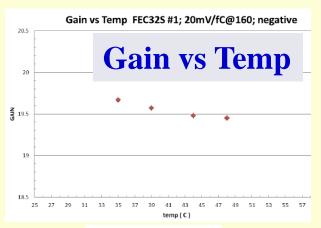


S.Movchan MPD TPC status

#### **Gain measurement: results**







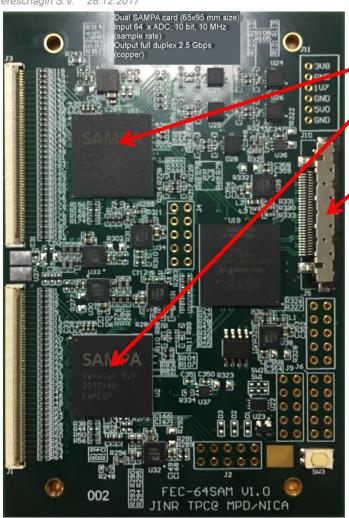
Gain 35°C = 19,67

Gain 48°C = 19,45

S.Movchan MPD TPC status

#### FEC64SAM v1.0 based on SAMPA rev.3

Vereschagin S.V. 28.12.2017



TPC/MPD Front-end card

Dual SAMPA card (65x95 mm size) Input 64 x ADC, 10 bit, 10 MHz (sample rate) Output full duplex 2.5 Gbps (copper)

#### **Status:**

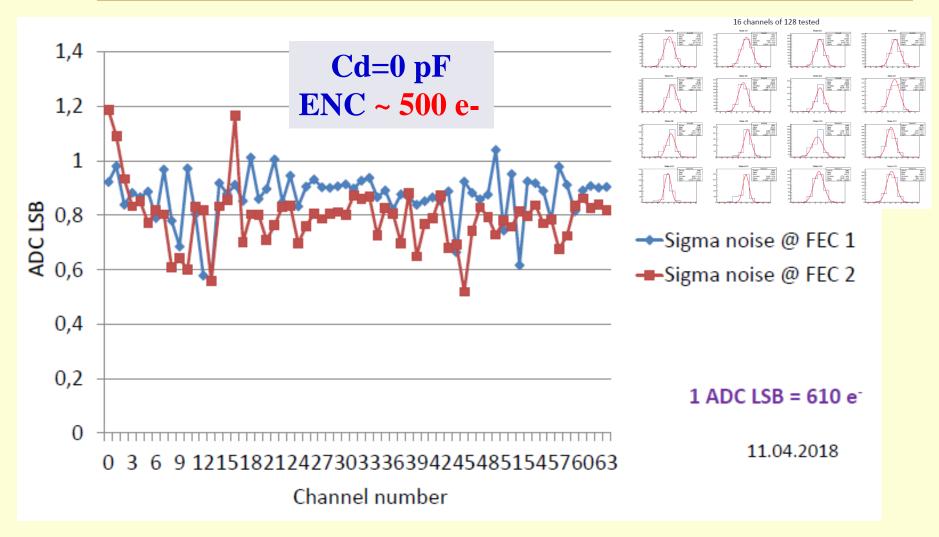
SAMPAs-FPGA communication – ok!
Trigger and synch – ok!
data transmission from FPGA to kit - ok!

#### **Plans:**

- board parameters study in progress
- build and test 512 ch system (8 boards)

- started

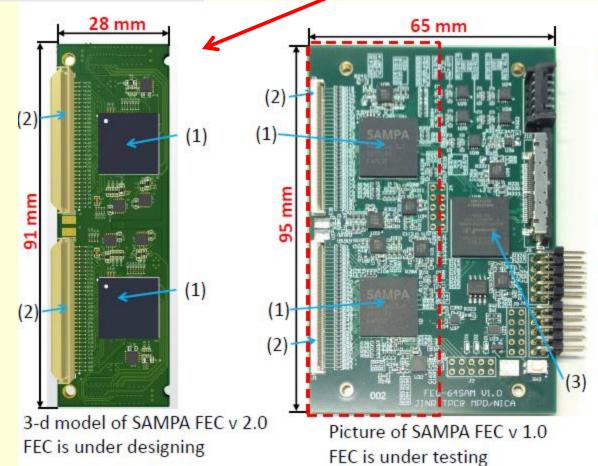
#### **Noise measurement: results**



15

#### **FE** board size minimization

#### Size 28x91 mm

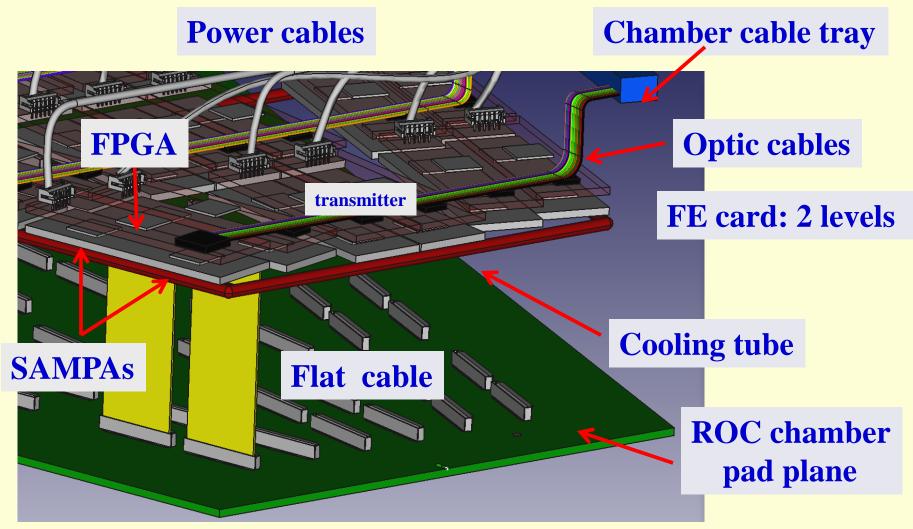


# The main parameters of FEC-64 SAMPA:

- Total number of registration channels
   64
- Dynamic range 100
   fC
- ADC resolution 10 bit
- ENC les than 1000e
- SAMPA configuration and management via FPGA
- Readout serial interface – up to 2.5 Gbps

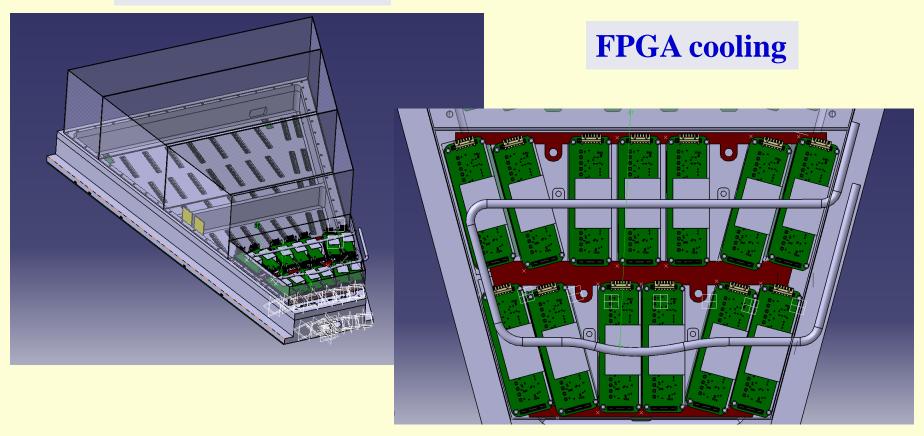
1) SAMPA ASIC - 32-channels; 2) Signal input connector; 3) FPGA with high-speed transceivers

## **ROC** chamber + electronics integration: concept

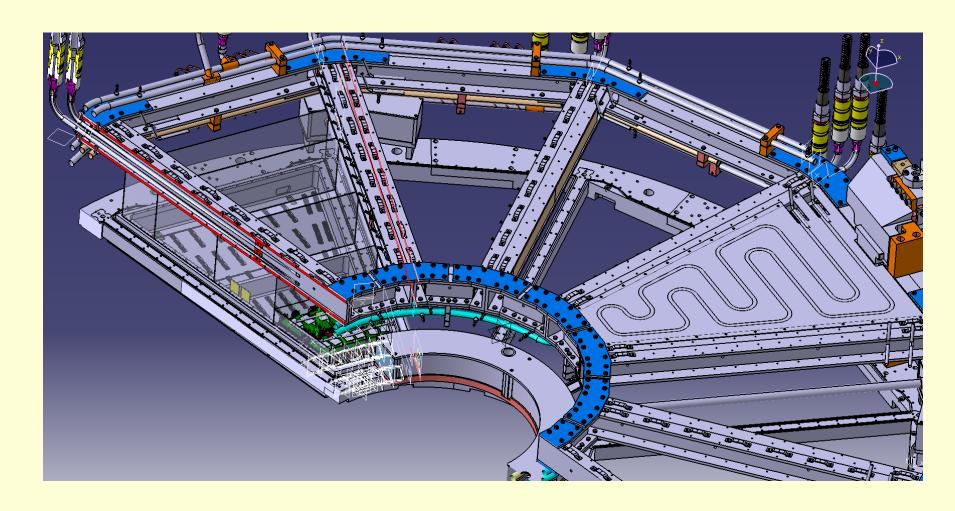


## **ROC** chamber + electronics integration

## **Shielding: 4 boxes**

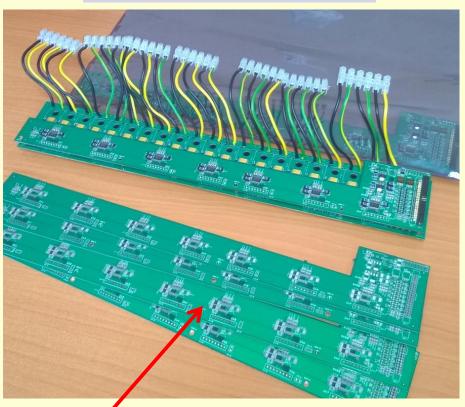


## **ROC** chamber + electronics integration



## INP BSU (Minsk): low voltage distribution board (LVDB)

## Prototype-01 (7 ch)



Prototype-02 (14 ch)



Slow control mezzanine board

Slow control integrated to LVDB board

## Gas, cooling and laser calibration systems: gas

#### Rack 2



#### Rack 1



Gas mixture	Ar + 10%CH <sub>4</sub>		
TPC gas flow, nominal	200 l/min		
TPC overpressure	$(2.0 \pm 0.1)$ mBar		
O <sub>2</sub> admixture	20 ppm		
H <sub>2</sub> O admixture	10 ppm		
External loop, refresh gas rate	30 l/min		
Fresh part of gas mixture add to external loop, range	(0-50) l/min		
TPC isolating gas	$N_2$		
N <sub>2</sub> gas flow	(5-20) l/min		

Status - commissioning (Bld.217)

# Gas system: commissioning (bld. 217)

## Racks

# TPC volume imitator

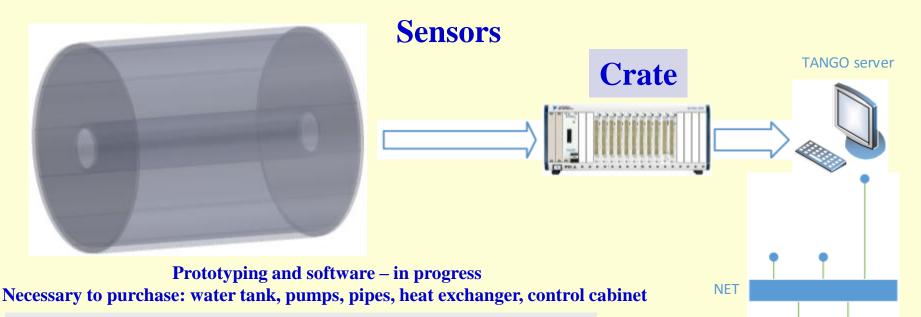
## **Gas supply**





S.Movchan MPD TPC status

## Gas, cooling and laser calibration systems: cooling

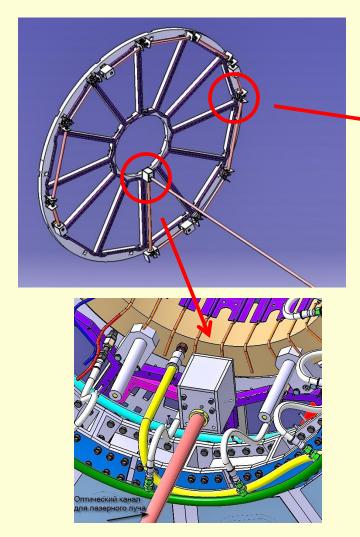


## **Cooling equipments and components purchased:**

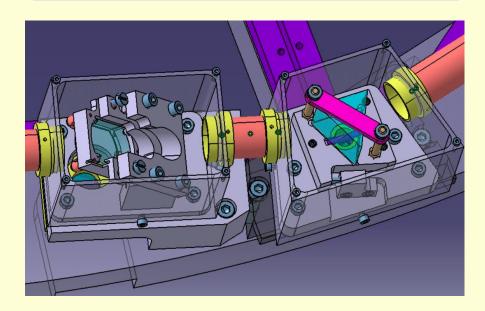
- crate NI PXle-1075 - 1 pc
- module NI TB 4357 (20ch) 10 pc
- module NI TB 4300 (8ch) - 1 pc
- -200 pc- temp. sensor
- 4 pc - pressure sensor

**Cooling system** prototype will be delivered to JINR **April 2018** 

## Gas, cooling and laser calibration systems: calibration

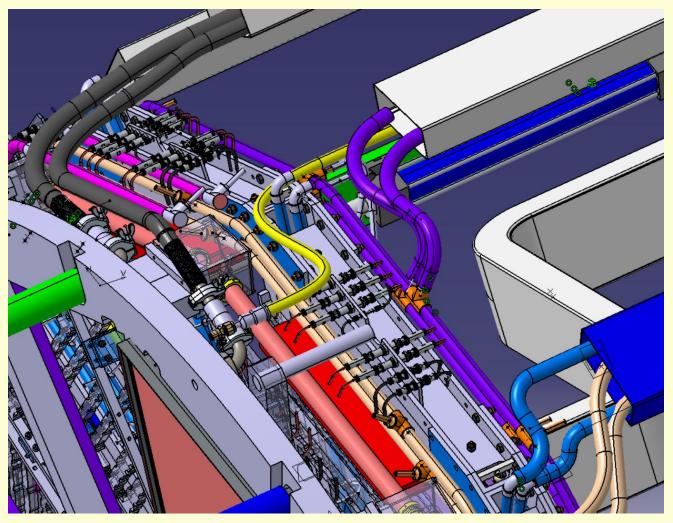


#### Semi transparency mirror & prism

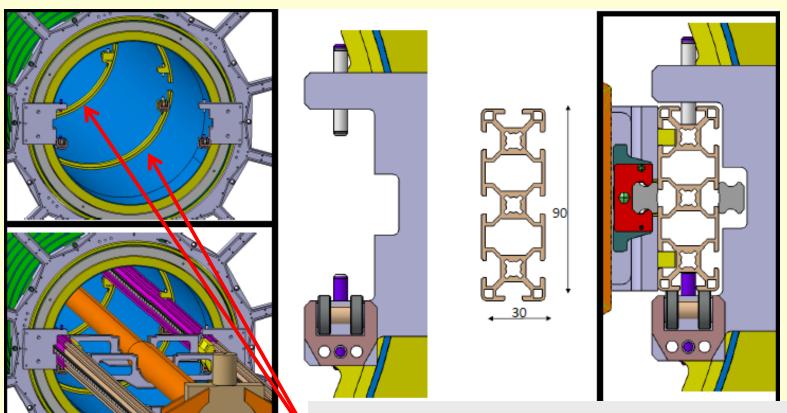


- inner beam distribution system design done
- 2 lasers (special option) delivered to JINR

# **TPC services: example of integration**



## MPD beam pipe concept: rail supports



2 inner support rings can be installed to C1 cylinder after finish TPC body assembly due to conflict with existing TPC assembly tooling

## **TPC time schedule**

Task Name	2016	2017	2018	2019	2020
	иши	ишши	ишши	ишши	иши
TPC assembly hall ready			h		
TPC parts assembly: HV electrode + field cage + 2 flanges + C1÷C4					
TPC body assembly and leak test					
ROC chamber manufacture (26 pc)					
24 ROCs Installation to TPC				*	
TPC electronics manufacture (FEC64SAM&RCU)				<u> </u>	<b>—</b>
FEC cards installation to ROC chambers					
TPC tests with cosmic and laser calibration system, Bld.217					
TPC transportation from Bld.217 to the MPD hall				İ	
TPC installation to MPD					7
TPC sub-systems installation (gas and cooling - MPD hall)					
TPC commissioning					

#### **Conclusion**

- TPC assembly hall ready
- TPC:
  - tooling for TPC body assembly ready
  - manipulator for ROC chamber installation May 30 2018
  - TPC parts: 4 cylinders -ok, 2 flanges ok, HV electrode May 2018
  - tooling for field cage manufacture and assembly June 2018
  - assembly of ROC chambers (26 pc) waiting for serial padplanes
  - Pad plane: quality is no so good ... new pre-series samples ordered PCB technology – March 2018, under tests Italy – March 30 -> April 30 2018
  - pre- serial ROC chambers: 1 pc tested
  - SAMPA rev.03 chips (30pc) tested (good 26 pc)
  - FEC32S board tested
  - FEC64SAM board with 2pc SAMPAs –tests started (ENC~500 e-)
  - new concept of FE electronics integration with ROC chamber in progress
  - gas system commissioning
  - cooling and laser calibration systems in progress
  - integration TPC to MPD in progress

#### **TPC commissioning - 2020**